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Vishay Semiconductors

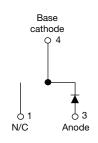
RoHS

HALOGEN

FREE

Ultralow V_F Hyperfast Rectifier for Discontinuous Mode PFC, 8 A FRED Pt[®]





D²PAK 2L (TO-263AB 2L)

PRIMARY CHARACTERISTICS						
I _{F(AV)}	8 A					
V_{R}	600 V					
V _F at I _F	0.81 V					
t _{rr} typ.	60 ns					
T _J max.	175 °C					
Package	D ² PAK 2L (TO-263AB 2L)					
Circuit configuration	Single					

FEATURES

- Benchmark ultralow forward voltage drop
- · Hyperfast recovery time
- · Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Meets JESD 201 class 2 whisker test
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

DESCRIPTION

State of the art, ultralow V_{F} , soft-switching hyperfast rectifiers optimized for discontinuous (critical) mode (DCM) power factor correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units and DVD AC/DC power supplies.

MECHANICAL DATA

Case: D²PAK 2L (TO-263AB 2L)

Molding compound meets UL 94 V-0 flammability rating **Terminals:** matte tin plated leads, solderable per

J-STD-002

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Peak repetitive reverse voltage	V_{RRM}		600	V			
Average rectified forward current	I _{F(AV)}	T _C = 160 °C	8				
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	175	Α			
Peak repetitive forward current	I _{FM}		16				
Operating junction and storage temperatures	T _J , T _{Stg}		-55 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Breakdown voltage, blocking voltage	V_{BR}, V_{R}	I _R = 100 μA	600	-	-			
Forward voltage	V _F	I _F = 8 A	-	0.96	1.05	V		
Forward voltage	v _F	I _F = 8 A, T _J = 150 °C	-	0.81	0.86			
Province and	I _R	V _R = V _R rated	-	0.05	5			
Reverse leakage current		T _J = 150 °C, V _R = V _R rated	-	20	100	μA		
Junction capacitance	C _T	V _R = 600 V	-	17	-	pF		
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH		



DYNAMIC RECOVERY CHARACTERISTICS (T _C = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST C	ONDITIONS	MIN.	TYP.	MAX.	UNITS	
		$I_F = 1 A$, $dI_F/dt =$	$I_F = 1 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		60	1		
Reverse recovery time	t _{rr}	T _J = 25 °C			170	-	ns	
		T _J = 125 °C	I _F = 8 A dI _F /dt = 200 A/μs V _R = 390 V	-	250	-		
Peak recovery current	I _{RRM}	T _J = 25 °C		-	15	-	A	
		T _J = 125 °C		-	20	-		
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	1.3	-	μC	
		T _J = 125 °C		-	2.6	-		

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C		
Thermal resistance, junction to case per leg	R _{thJC}		-	1.4	2			
Thermal resistance, junction to ambient per leg	R _{thJA}	Typical socket mount	-	-	70	°C/W		
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-	0, 11		
Weight			-	2.0	-	g		
Weight			-	0.07	-	oz.		
Mounting torque			6.0	_	12	kgf · cm		
wounting torque			(5.0)	_	(10)	(lbf · in)		
Marking device		Case style D ² PAK 2L (TO-263AB 2L)	8ETL06SH		·			

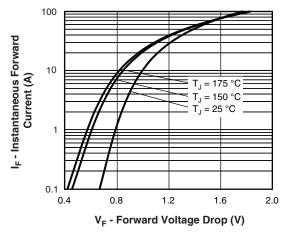


Fig. 1 - Typical Forward Voltage Drop Characteristics

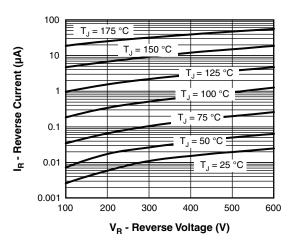


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

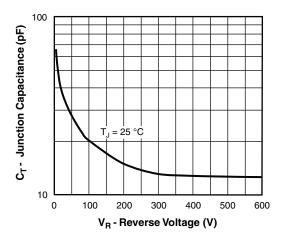


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

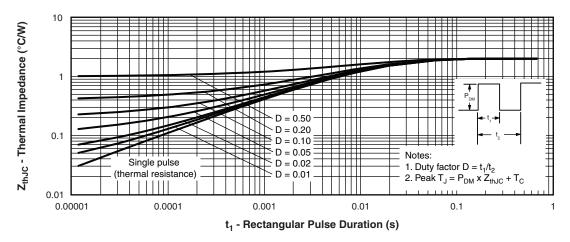


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

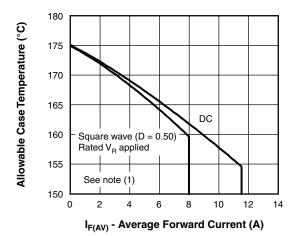


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

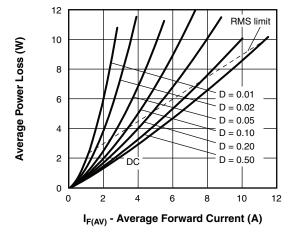


Fig. 6 - Forward Power Loss Characteristics

Note

⁽¹⁾ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{thJC}; Pd = forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = rated V_R



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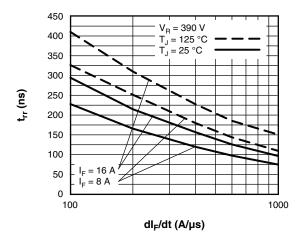


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

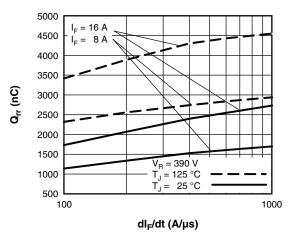
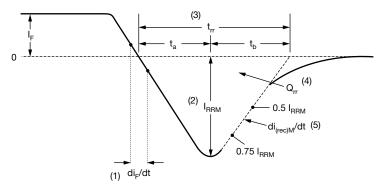


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm l_F$ to point where a line passing through 0.75 $\rm l_{RRM}$ and 0.50 $\rm l_{RRM}$ extrapolated to zero current.
- (4) ${\rm Q_{rr}}$ area under curve defined by ${\rm t_{rr}}$ and ${\rm I_{RRM}}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

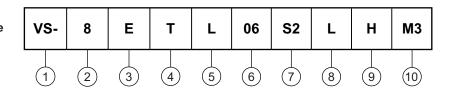
(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



Vishay Semiconductors product

Current rating (8 A)

3 - E = single diode

T = D²PAK (TO-262) package

5 - L = ultralow V_F hyperfast recovery

6 - Voltage rating (06 = 600 V)

7 - • S2 = = true 2 pin D²PAK

None = tube (50 pieces)

L = tape and reel (left oriented, for D²PAK package)
If needed different orientation/packaging, please contact factory

9 - H = lead (Pb)-free

- M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

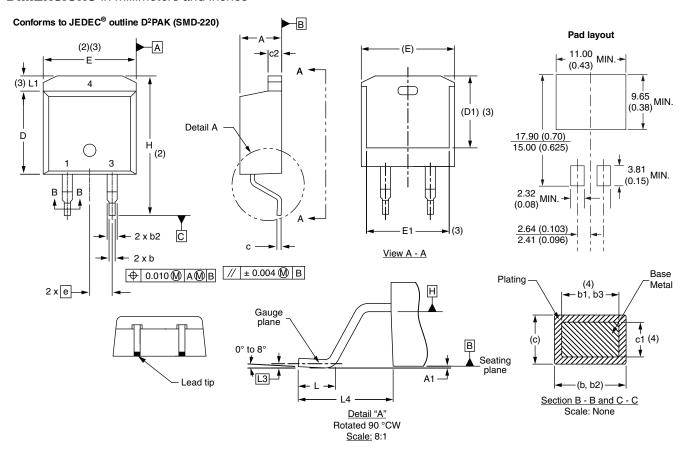
ORDERING INFORMATION						
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-8ETL06S2LHM3	800	800	13" diameter reel			

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?96683			
Part marking information	www.vishay.com/doc?96693			
Packaging information	www.vishay.com/doc?95032			
SPICE model	www.vishay.com/doc?96055			



D²PAK 2L (TO-263AB 2L)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INCHES		NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIM	ETERS	INCHES		NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	2.54 BSC		0.100 BSC	
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L3	0.25	0.25 BSC		BSC	
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



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